

OPA2107

## Precision Dual *Difet*® OPERATIONAL AMPLIFIER

### FEATURES

- VERY LOW NOISE:  $8\text{nV}/\sqrt{\text{Hz}}$  at 10kHz
- LOW  $V_{OS}$ : 500 $\mu\text{V}$  max
- LOW DRIFT: 5 $\mu\text{V}/^\circ\text{C}$  max
- LOW  $I_B$ : 5pA max
- FAST SETTLING TIME: 2 $\mu\text{s}$  to 0.01%
- UNITY-GAIN STABLE

### APPLICATIONS

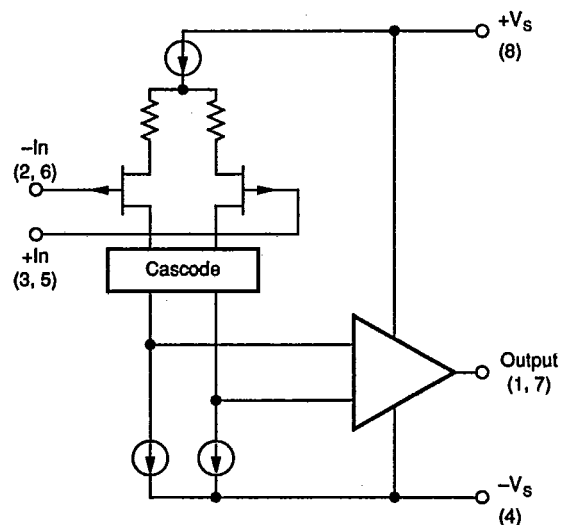
- DATA ACQUISITION
- DAC OUTPUT AMPLIFIER
- OPTOELECTRONICS
- HIGH-IMPEDANCE SENSOR AMPS
- HIGH-PERFORMANCE AUDIO CIRCUITRY
- MEDICAL EQUIPMENT, CT SCANNERS

### DESCRIPTION

The OPA2107 dual operational amplifier provides precision *Difet* performance with the cost and space savings of a dual op amp. It is useful in a wide range of precision and low-noise analog circuitry and can be used to upgrade the performance of designs currently using BIFET® type amplifiers.

The OPA2107 is fabricated on a proprietary dielectrically isolated (*Difet*) process. This holds input bias currents to very low levels without sacrificing other important parameters, such as input offset voltage, drift and noise. Laser-trimmed input circuitry yields excellent DC performance. Superior dynamic performance is achieved, yet quiescent current is held to under 2.5mA per amplifier. The OPA2107 is unity-gain stable.

The OPA2107 is available in plastic DIP, metal TO-99, and SOIC packages. Industrial and Military temperature range versions are available.



*Difet*® Burr-Brown Corp.  
BIFET® National Semiconductor

International Airport Industrial Park • Mailing Address: PO Box 11400 • Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd. • Tucson, AZ 85706  
Tel: (602) 746-1111 • Twx: 910-952-1111 • Cable: BBRCORP • Telex: 066-6491 • FAX: (602) 889-1510 • Immediate Product Info: (800) 548-6132

# SPECIFICATIONS

T<sub>A</sub> = +25°C, V<sub>S</sub> = ±15V unless otherwise noted.

PARAMETER	CONDITION	OPA2107AM, SM, AP, AU			OPA2107BM			UNITS	
		MIN	TYP	MAX	MIN	TYP	MAX		
<b>OFFSET VOLTAGE<sup>(1)</sup></b> Input Offset Voltage Over Specified Temperature SM Grade Average Drift Over Specified Temperature Power Supply Rejection	V <sub>CM</sub> = 0V		100	1mV		50	500	μV	
			0.5	2		0.2	1	mV	
	V <sub>S</sub> = ±10 to ±18V		0.8	2.5				mV	
			3	10		2	5	μV/°C	
		80	96		84	100	dB		
<b>INPUT BIAS CURRENT<sup>(1)</sup></b> Input Bias Current Over Specified Temperature SM Grade Input Offset Current Over Specified Temperature SM Grade	V <sub>CM</sub> = 0V		4	10		2	5	pA	
				0.25	1.5		0.15	1	nA
	V <sub>CM</sub> = 0V			4	35				nA
				1	8		0.5	3	pA
					1	1		0.5	nA
			1	28				nA	
<b>INPUT NOISE</b> Voltage: f = 10Hz f = 100Hz f = 1kHz f = 10kHz BW = 0.1 to 10Hz BW = 10 to 10kHz Current: f = 0.1Hz thru 20kHz BW = 0.1Hz to 10Hz	R <sub>S</sub> = 0		30			*		nV/√Hz	
			12			*		nV/√Hz	
			9			*		nV/√Hz	
			8			*		nV/√Hz	
			1.2			*		μVp-p	
			0.85			*		μVrms	
			1.2			0.9		fA/√Hz	
			23			17		fAp-p	
<b>INPUT IMPEDANCE</b> Differential Common-Mode			10 <sup>13</sup>    2			*		Ω    pF	
			10 <sup>14</sup>    4			*		Ω    pF	
<b>INPUT VOLTAGE RANGE</b> Common-Mode Input Range Over Specified Temperature SM Grade Common-Mode Rejection	V <sub>CM</sub> = ±10V		±10.5	±11		*	*	V	
			±10.2	±10.5		*	*	V	
			±10	±10.3				V	
			80	94		84	100	dB	
<b>OPEN-LOOP GAIN</b> Open-Loop Voltage Gain Over Specified Temperature SM Grade	V <sub>O</sub> = ±10V, R <sub>L</sub> = 2kΩ		82	96		84	100	dB	
			80	94		82	96	dB	
			80	92				dB	
<b>DYNAMIC RESPONSE</b> Slew Rate Settling Time: 0.1% 0.01% Gain-Bandwidth Product THD + Noise Channel Separation	G = +1 G = -1, 10V Step		13	18		*	*	V/μs	
				1.5		*	*	μs	
	G = 100 G = +1, f = 1kHz f = 100Hz, R <sub>L</sub> = 2kΩ			2		*	*	μs	
				4.5		*	*	MHz	
				0.001		*	*	%	
				120		*	*	dB	
<b>POWER SUPPLY</b> Specified Operating Voltage Operating Voltage Range Current			±4.5	±15		*	*	V	
				±4.5	±18		*	V	
				±5		*	*	mA	
<b>OUTPUT</b> Voltage Output Over Specified Temperature SM Grade Short Circuit Current Output Resistance, Open-Loop Capacitive Load Stability	R <sub>L</sub> = 2kΩ		±11	±12		*	*	V	
			±10.5	±11.5		*	*	V	
			±10.2	±11.3		*	*	V	
	1MHz G = +1		±10	±40		*	*	mA	
				70		*	*	Ω	
				1000		*	*	pF	
<b>TEMPERATURE RANGE</b> Specification AP, AU, AM, BM SM Operating AP, AU AM, BM, SM Storage AP, AU AM, BM, SM Thermal Resistance (θ <sub>J,A</sub> ) AP AU AM, BM, SM			-25	+85		*	*	°C	
			-55	+125					°C
			-25	+85		*	*	°C	
			-55	+125		*	*	°C	
			-40	+125		*	*	°C	
			-65	+150		*	*	°C	
				90			*	°C/W	
				175			*	°C/W	
				200			*	°C/W	
							*		
							*		

\* Specifications same as OPA2107AM.

NOTE: (1) Specified with devices fully warmed up.

T-79-15

**ORDERING INFORMATION**

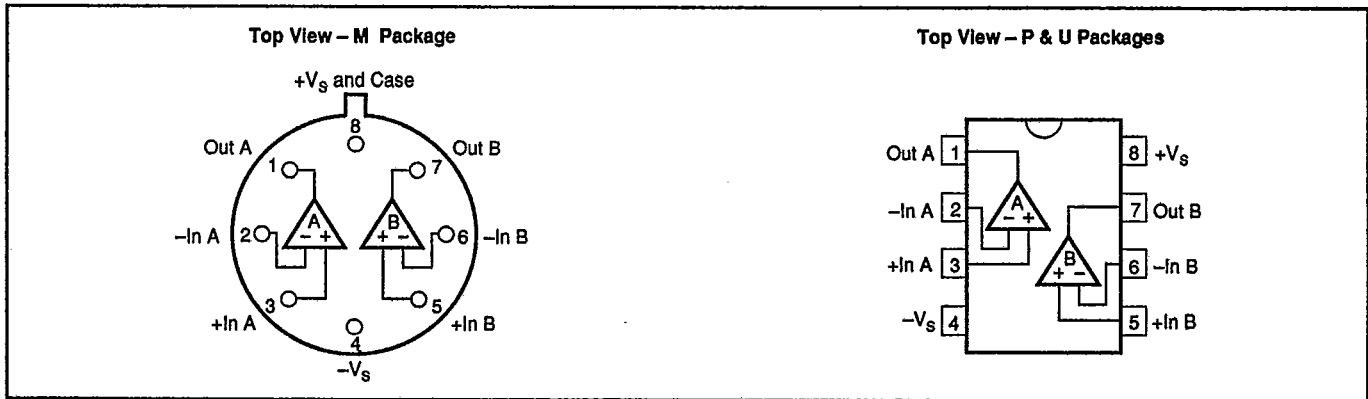
MODELS	PACKAGE	SPECIFICATION TEMPERATURE RANGE	USA OEM PRICES		
			1-24	25-99	100+
OPA2107AP	Plastic DIP	-25 to +85°C	\$10.80	\$7.50	\$5.70
OPA2107AM	Metal TO-99	-25 to +85°C	13.45	10.20	8.05
OPA2107BM	Metal TO-99	-25 to +85°C	19.20	13.95	10.90
OPA2107SM	Metal TO-99	-55 to +125°C	34.65	25.95	19.80
OPA2107AU	SO-8 SOIC	-25 to +85°C	12.40	8.65	6.55

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage .....	±18V
Input Voltage Range .....	±V <sub>s</sub> ±2V
Differential Input Voltage .....	Total V <sub>s</sub> ±4V
Operating Temperature	
M Package .....	-55°C to +125°C
P and U Packages .....	-25°C to +85°C
Storage Temperature	
M Package .....	-65°C to +150°C
P and U Packages .....	-40°C to +125°C
Output Short Circuit to Ground (T <sub>A</sub> = +25°C) .....	Continuous
Junction Temperature .....	+175°C
Lead Temperature	
M and P Packages (soldering, 10s) .....	+300°C
U Package, SOIC (3s) .....	+260°C

The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.

**PIN CONFIGURATIONS**



**MECHANICAL**

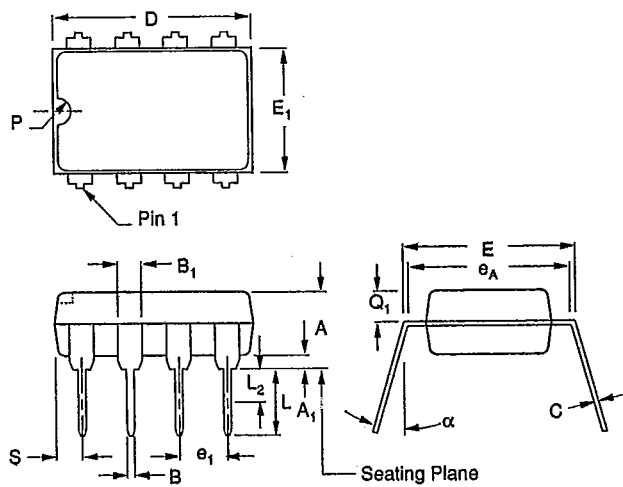
**M Package — Metal TO-99**

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.335	.370	8.51	9.40
B	.305	.335	7.75	8.51
C	.165	.185	4.19	4.70
D	.016	.021	0.41	0.53
E	.010	.040	0.25	1.02
F	.010	.040	0.25	1.02
G	.200 BASIC		5.08 BASIC	
H	.028	.034	0.71	0.86
J	.029	.045	0.74	1.14
K	.500	—	12.7	—
L	.110	.160	2.79	4.06
M	45° BASIC		45° BASIC	
N	.095	.105	2.41	2.67

NOTE: Leads in true position within 0.01" (0.25mm) R at MMC at seating plane. Pin numbers shown for reference only. Numbers may not be marked on package.

**MECHANICAL (CONT)**

**P Package — 8-Pin Plastic DIP**

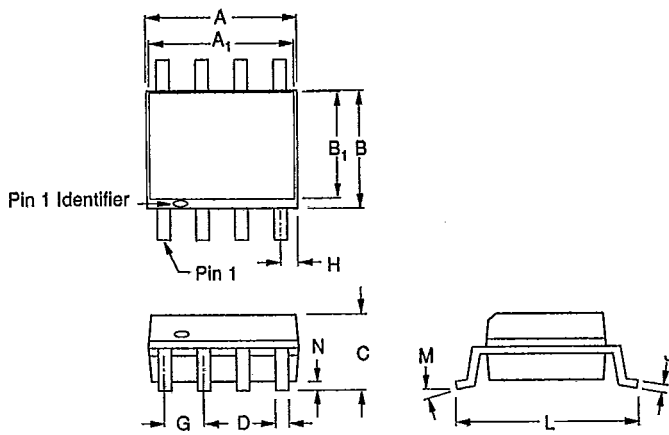


DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.155	.200	3.94	5.08
A <sub>1</sub>	.020	.050	0.51	1.27
B	.014	.020	0.36	0.51
B <sub>1</sub>	.045	.065	1.14	1.65
C	.008	.012	0.20	0.30
D <sup>(1)</sup>	.370	.400	9.40	10.16
E	.300	.325	7.62	8.26
E <sub>1</sub>	.240	.260	6.10	6.60
e <sub>1</sub>	.100 BASIC		2.54 BASIC	
e <sub>A</sub>	.300 BASIC		7.62 BASIC	
L	.125	.150	3.18	3.81

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
L <sub>2</sub> <sup>(2)</sup>	0	.030	0.00	0.76
α	0°	15°	0°	15°
P	.015	.050	0.38	1.270
Q <sub>1</sub>	.040	.075	1.02	1.91
S <sup>(1)</sup>	.015	.050	0.38	1.27

(1) Not JEDEC Std.  
 (2) e<sub>1</sub> and e<sub>A</sub> apply in zone L<sub>2</sub> when unit installed.  
 NOTE: Leads in true position within 0.01" (0.25mm) R at MMC at seating plane.

**U Package — 8-Pin SOIC**



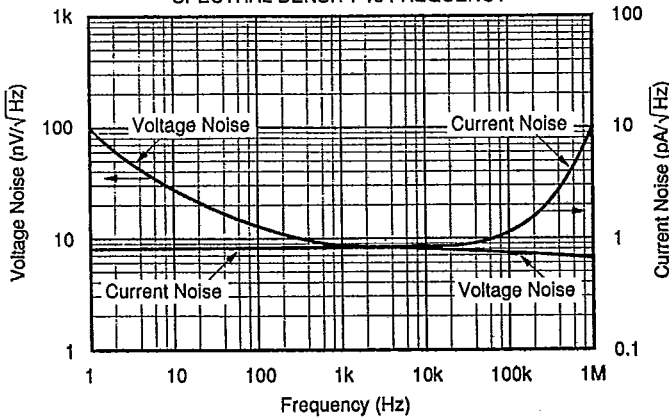
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.201	4.70	5.11
A <sub>1</sub>	.178	.201	4.52	5.11
B	.146	.162	3.71	4.11
B <sub>1</sub>	.130	.149	3.30	3.78
C	.054	.145	1.37	3.69
D	.015	.019	0.38	0.48
G	.050 BASIC		1.27 BASIC	
H	.018	.026	0.46	0.66
J	.008	.012	0.20	0.30
L	.220	.252	5.59	6.40
M	0°	10°	0°	10°
N	.000	.012	0.00	0.30

NOTE: Leads in true position within 0.01" (0.25mm) R at MMC at seating plane.

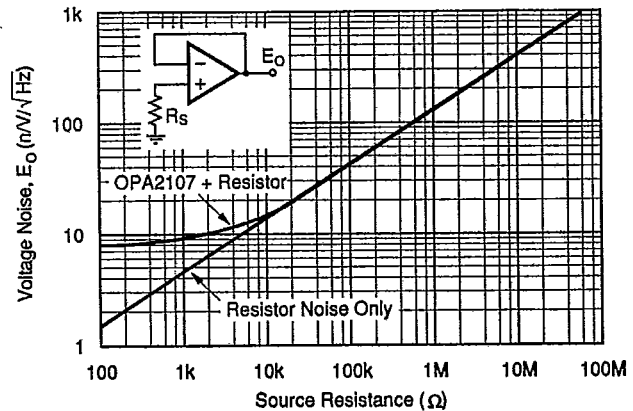
**TYPICAL PERFORMANCE CURVES**

T<sub>A</sub> = +25°C, V<sub>S</sub> = ±15V unless otherwise noted.

**INPUT VOLTAGE AND CURRENT NOISE SPECTRAL DENSITY vs FREQUENCY**

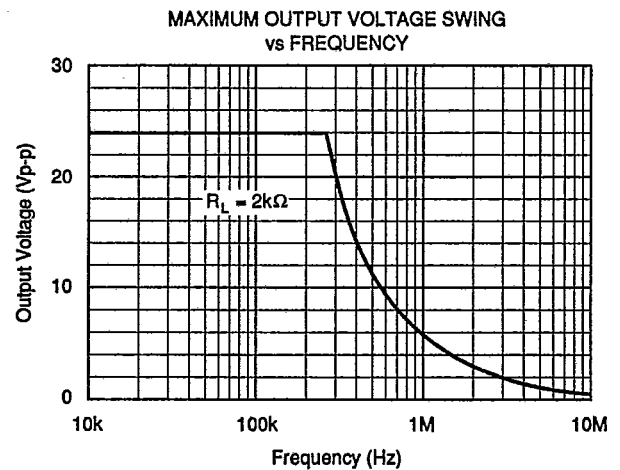
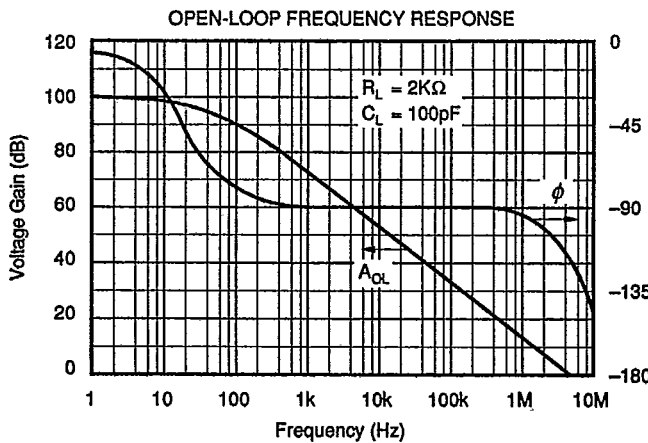
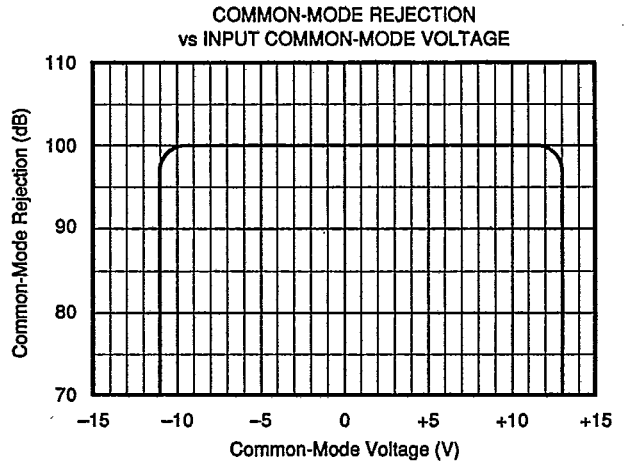
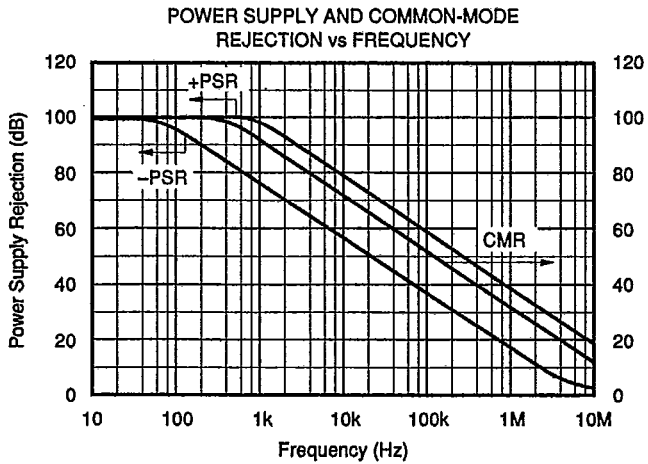
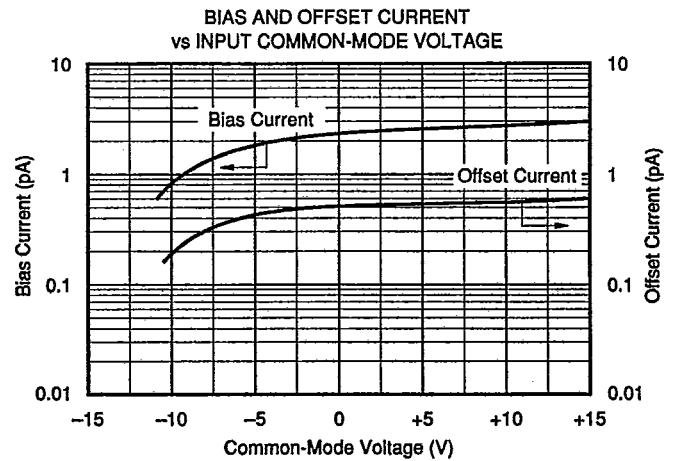
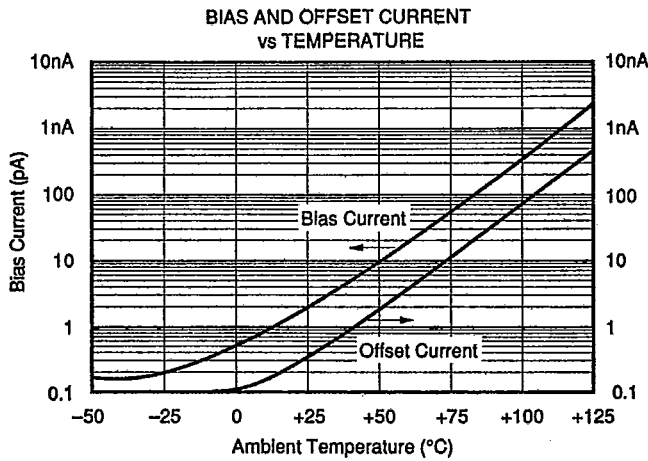


**TOTAL INPUT VOLTAGE NOISE SPECTRAL DENSITY at 1kHz vs SOURCE RESISTANCE**



# TYPICAL PERFORMANCE CURVES (CONT)

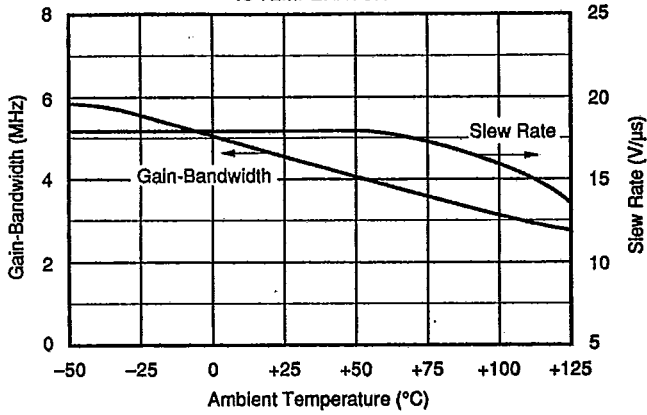
$T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$  unless otherwise noted.



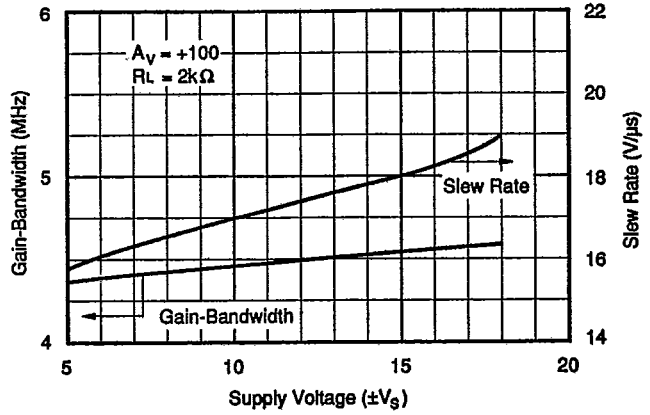
# TYPICAL PERFORMANCE CURVES (CONT)

$T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$  unless otherwise noted.

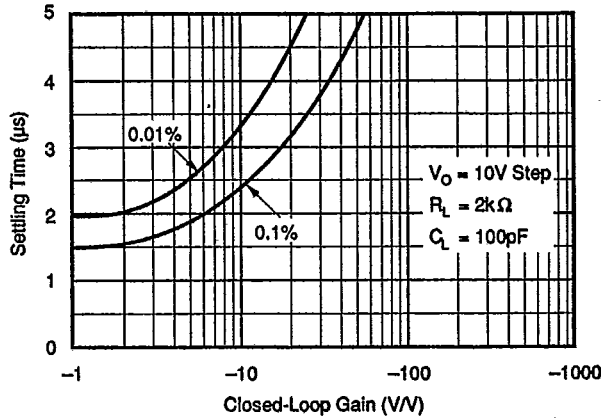
GAIN-BANDWIDTH AND SLEW RATE vs TEMPERATURE



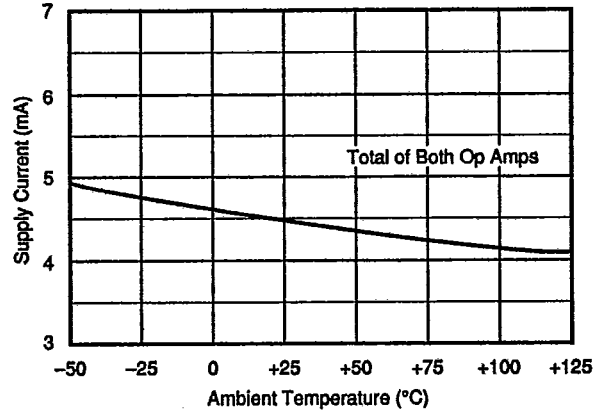
GAIN-BANDWIDTH AND SLEW RATE vs SUPPLY VOLTAGE



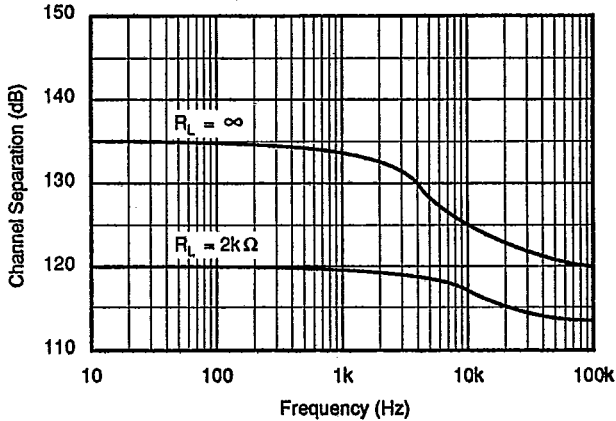
SETTLING TIME vs CLOSED-LOOP GAIN



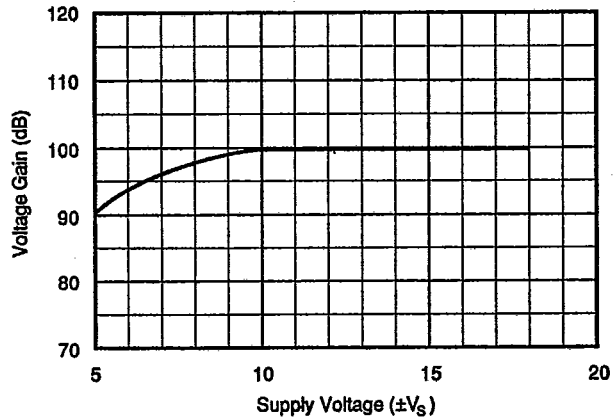
SUPPLY CURRENT vs TEMPERATURE



CHANNEL SEPARATION vs FREQUENCY

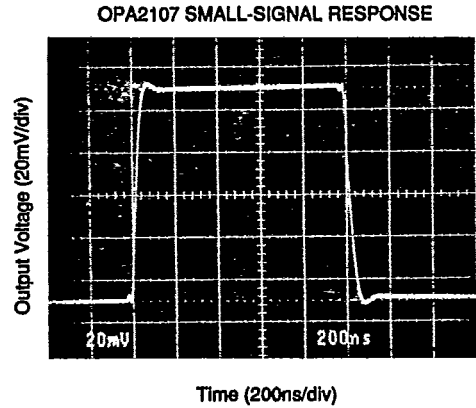
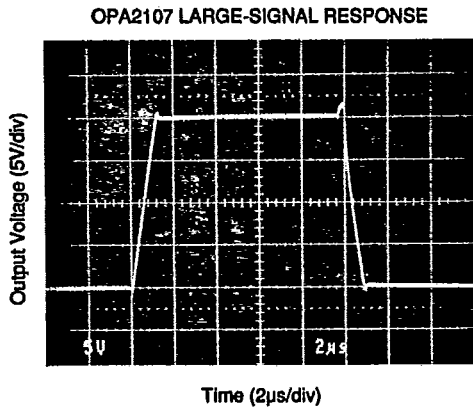
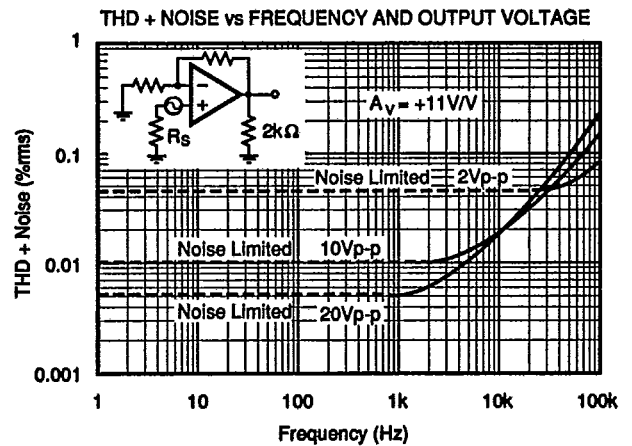
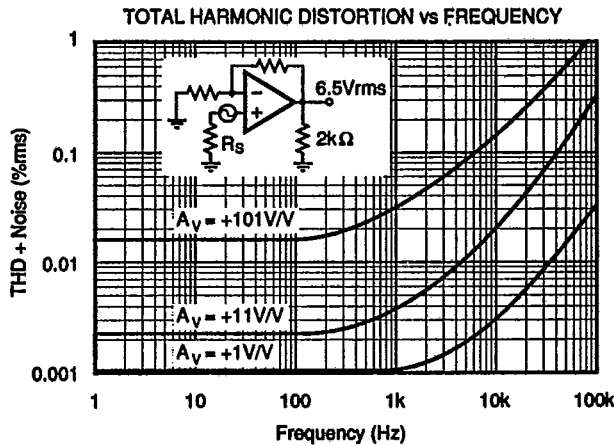


OPEN-LOOP GAIN vs SUPPLY VOLTAGE



# TYPICAL PERFORMANCE CURVES (CONT)

$T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$  unless otherwise noted.



## APPLICATIONS INFORMATION AND CIRCUITS

The OPA2107 is unity-gain stable and has excellent phase margin. This makes it easy to use in a wide variety of applications.

Power supply connections should be bypassed with capacitors positioned close to the amplifier pins. In most cases, 0.1µF ceramic capacitors are adequate. Applications with larger load currents and fast transient signals may need up to 1µF tantalum bypass capacitors.

### INPUT BIAS CURRENT

The OPA2107's *Difet* input stages have very low input bias current—an order of magnitude lower than BIFET op amps.

Circuit board leakage paths can significantly degrade performance. This is especially evident with the SO-8 surface-mount package where pin-to-pin dimensions are particularly small. Residual soldering flux, dirt, and oils, which conduct leakage current, can be removed by proper cleaning. In most instances a two-step cleaning process is adequate using a clean organic solvent rinse followed by de-ionized water. Each rinse should be followed by a 30-minute bake at 85°C.

A circuit board guard pattern effectively reduces errors due to circuit board leakage (Figure 1). By encircling critical high impedance nodes with a low impedance connection at the same circuit potential, any leakage currents will flow harmlessly to the low impedance node. Guard traces should be placed on all levels of a multiple-layer circuit board.

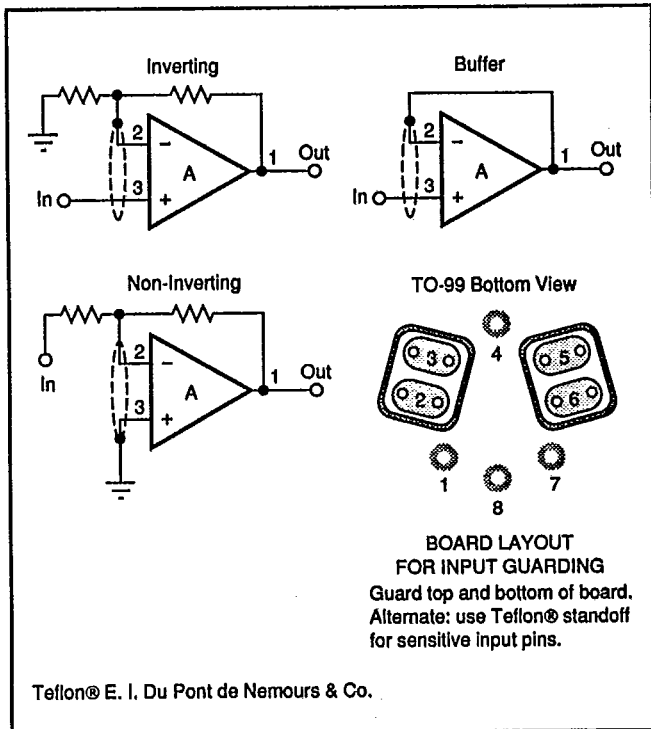


FIGURE 1. Connection of Input Guard.

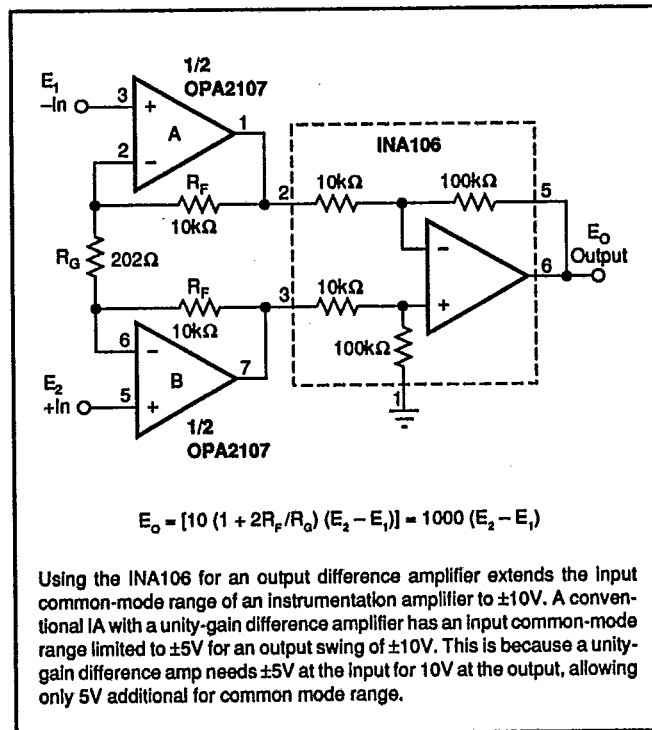


FIGURE 3. Precision Instrumentation Amplifier.

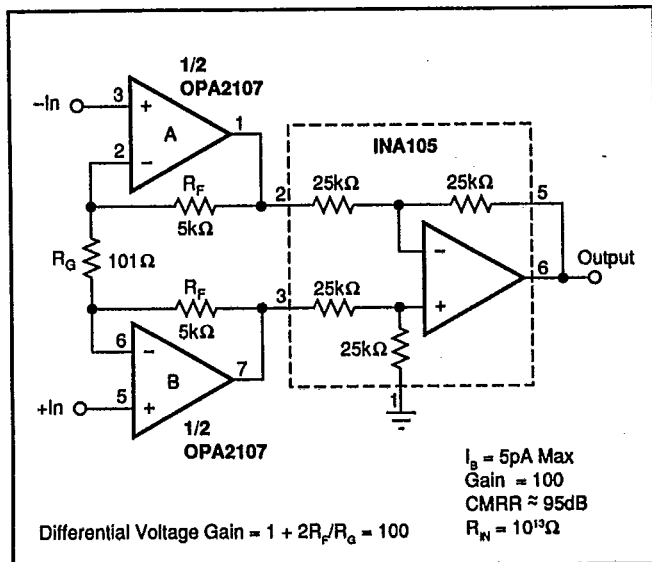


FIGURE 2. FET Input Instrumentation Amplifier.